MOSFET Silicon N-Channel MOS

1. Applications

Boost PFC switch, Half bridge or Asymmetric half bridge or Series resonance half bridge and full bridge topologies.
Server power, Telecom power, EV charging, Solar inverter, UPS Application.
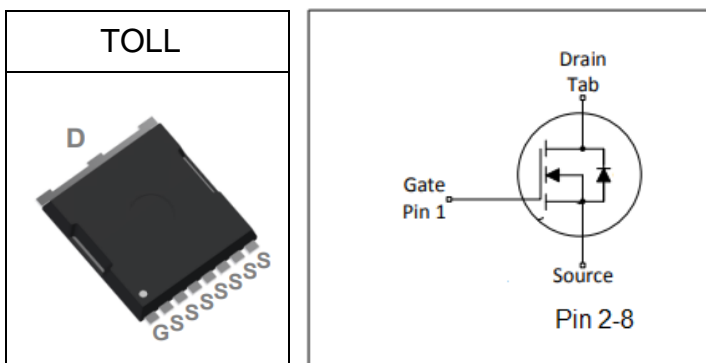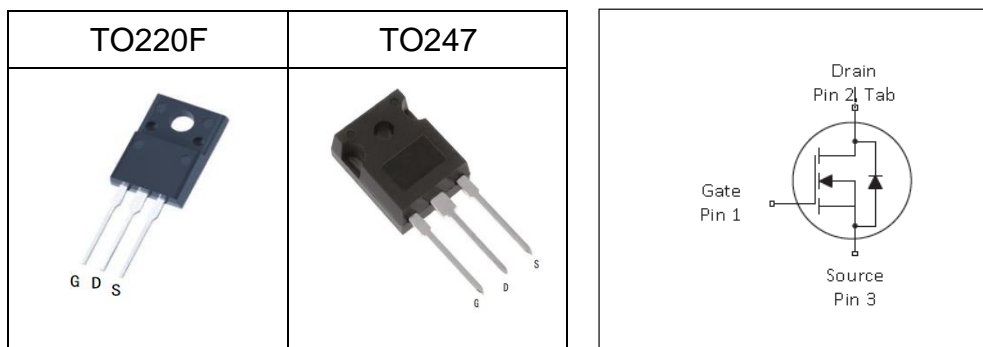
2. Features

Low drain-source on-resistance: RDS(ON) = 0.105Ω (typ.)
Easy to control Gate switching
Enhancement mode: Vth = 3 to 5 V

Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS} @ $T_{j,max}$	700	V
$R_{DS(on),max}$	120	mΩ
$Q_{g,typ}$	55.4	nC
$I_{D,pulse}$	90	A
Body diode dv/dt	50	V/ns

3. Packaging and Internal Circuit

Part Name	Package	Marking
ASW65R120EFD	TO247	ASW65R120EFD
ASA65R120EFD	TO220F	ASA65R120EFD
ASR65R120EFD	TOLL-8L	ASR65R120EFD

1 Maximum ratings

at T_j = 25°C, unless otherwise specified

Table 2   Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current[1]	I_D		-	30	A	T_C=25°C
Pulsed drain current[2]	$I_{D,pulse}$	-	-	90	A	T_C=25°C
Avalanche energy, single pulse	E_{AS}	-	-	1216	mJ	Tc=25°C,VDD=50V, L=10mH, RG=25Ω
Avalanche current, single pulse	I_{AR}	-	-	10.9	A	Tc=25°C,VDD=50V,L=10mH, RG=25Ω
MOSFET dv/dt ruggedness	dv/dt	-	-	36.2	V/ns	V_{DS}=0...400V
Gate source voltage (static)	V_{GS}	-20	-	20	V	static;
Gate source voltage (dynamic)	V_{GS}	-30	-	30	V	AC (f>1 Hz)
Power dissipation(TO247)	P_{tot}	-	-	277.8	W	T_C=25°C
Power dissipation (TO220F)	P_{tot}	-	-	36.5	W	T_C=25°C
Storage temperature	T_{stg}	-55	-	150	°C	
Operating junction temperature	T_j	-55	-	150	°C	
Soldering Temperature Distance of 1.6mm from case for 10s	T_L			260	°C	
Reverse diode dv/dt[3]	dv/dt	-	-	50	V/ns	V_{DS}=0...400V, I_{SD}<= I_D, T_j=25°C see table 8

[1] Limited by $T_{j,max}$. Maximum Duty Cycle D = 0.50
[2] Pulse width t_p limited by $T_{j,max}$
[3] Identical low side and high side switch with identical R_G

2   Thermal characteristics

Table 3   Thermal characteristics (TO220F)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	3.4	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	°C/W	device on PCB, minimal footprint

Thermal characteristics(TO247)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	-	0.45	°C/W	-
Thermal resistance, junction - ambient	R_{thJA}	-	-	57	°C/W	device on PCB, minimal footprint

3   Electrical characteristics

at T_j=25°C, unless otherwise specified

Table 4   Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	655	-	-	V	V_{GS}=0V, I_D=250uA
Gate threshold voltage	$V_{(GS)th}$	3		5	V	V_{DS}= V_{GS}, I_D=250uA
Zero gate voltage drain current	I_{DSS}	-	-	2	uA	V_{DS}=650V, V_{GS}=0V, T_j=25°C
Gate-source leakage current	I_{GSS}	-	-	100	nA	V_{GS}=30V, V_{DS}=0V
Drain-source on-state resistance	$R_{DS(on)}$	-	0.105	0.120	Ω	V_{GS}=10V, I_D=14A, T_j=25°C
Gate resistance (Intrinsic)	R_G	-	12.6	-	Ω	f=1MHz, open drain

Table 5   Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	C_{iss}	-	2657	-	pF	V_{GS}=0V, V_{DS}=100V, f=1MHz
Output capacitance	C_{oss}	-	89	-	pF	V_{GS}=0V, V_{DS}=100V, f=1MHz
Reverse transfer capacitance	C_{rss}	-	2	-	pF	V_{GS}=0V, V_{DS}=100V, f=1MHz
Turn-on delay time	$t_{d(on)}$	-	29.6	-	ns	V_{DD}=400V, V_{GS}=10V, I_D=19A, R_G=2Ω; see table 9
Rise time	t_r	-	31.3	-	ns	V_{DD}=400V, V_{GS}=10V, I_D=19A, R_G=2Ω; see table 9
Turn-off delay time	$t_{d(off)}$	-	94.6	-	ns	V_{DD}=400V, V_{GS}=10V, I_D=19A, R_G=2Ω; see table 9
Fall time	t_f	-	9.1	-	ns	V_{DD}=400V, V_{GS}=10V, I_D=19A, R_G=2Ω; see table 9

Table 6   Gate charge characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	15	-	nC	V_{DD}=400V, I_D=19A, V_{GS}=0 to 10V
Gate to drain charge	Q_{gd}	-	20.2	-	nC	V_{DD}=400V, I_D=19A, V_{GS}=0 to 10V
Gate charge total	Q_g	-	55.4	-	nC	V_{DD}=400V, I_D=19A, V_{GS}=0 to 10V
Gate plateau voltage	$V_{plateau}$	-	5.9	-	V	V_{DD}=400V, I_D=19A, V_{GS}=0 to 10V

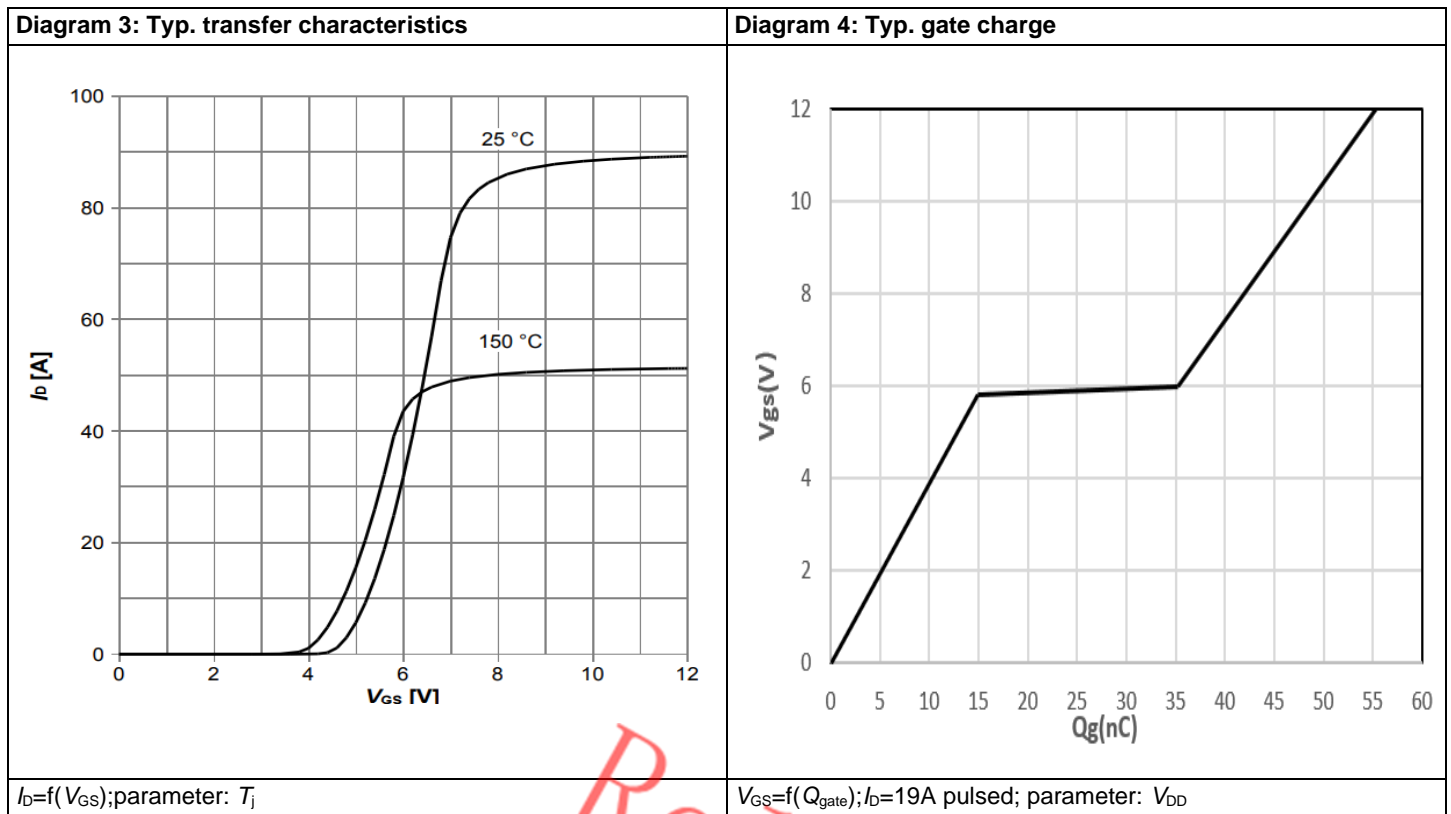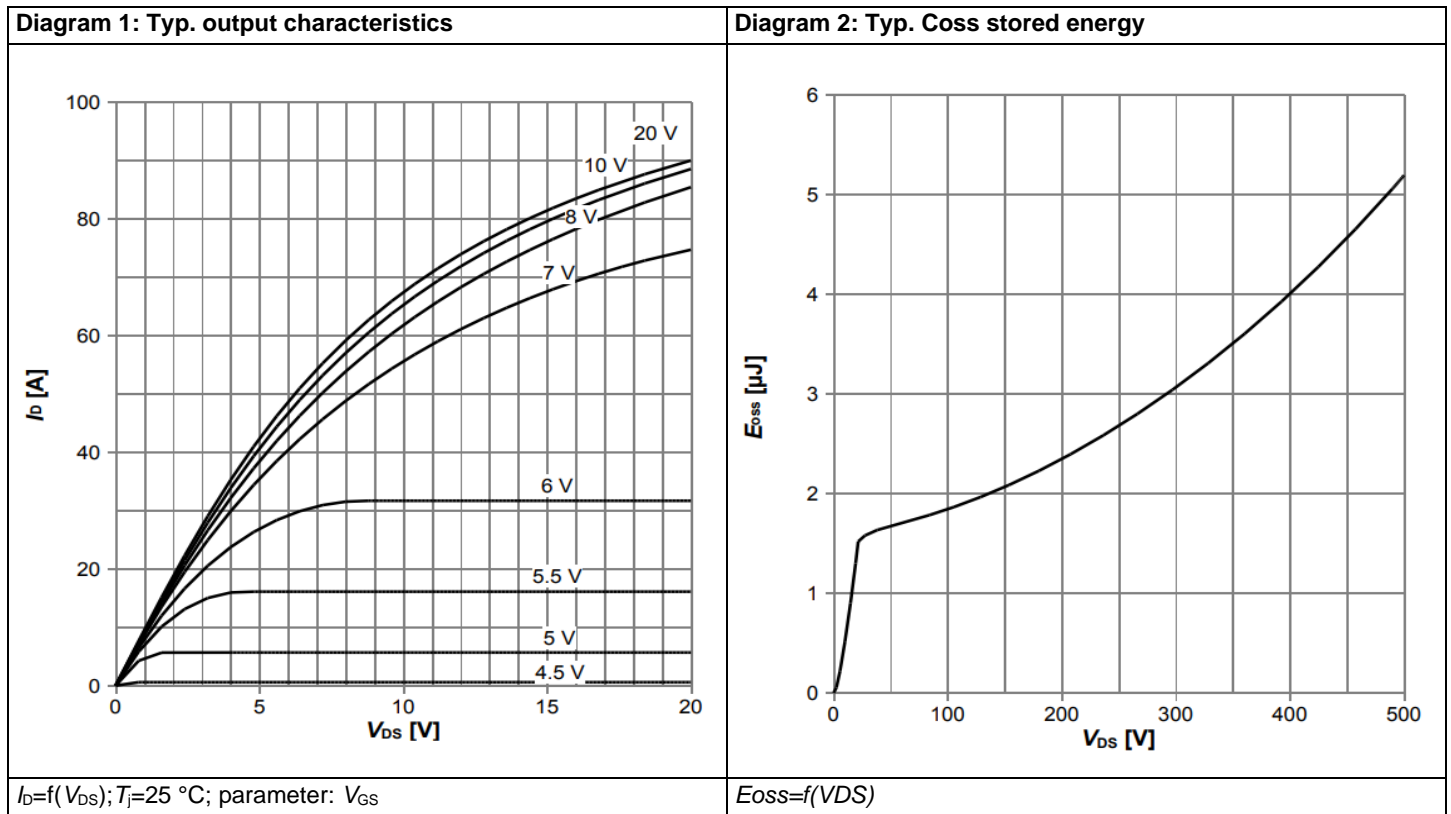**Table 7   Reverse diode characteristics**

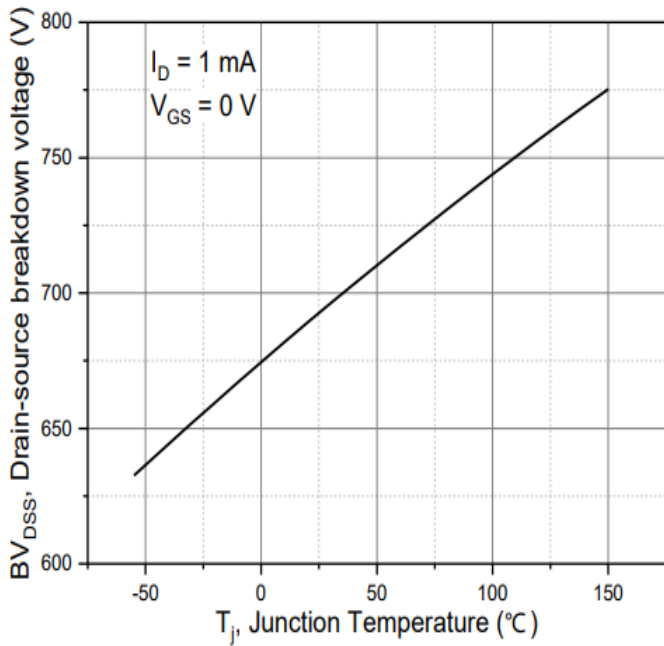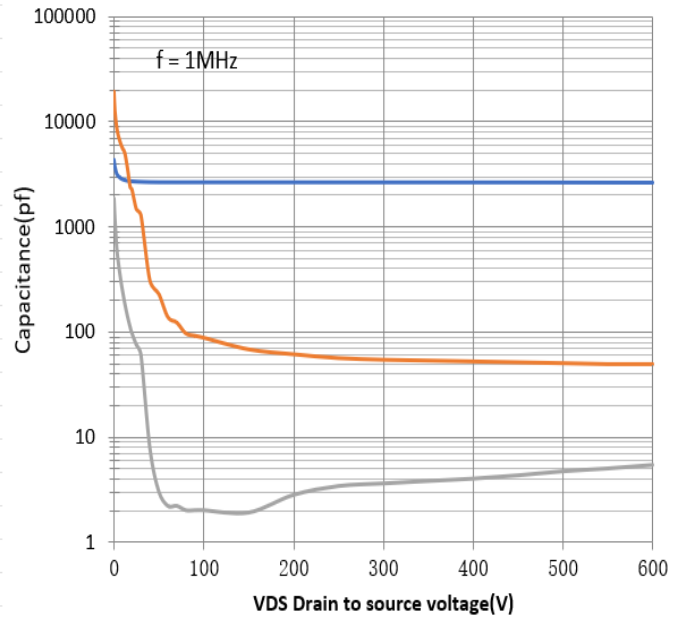| Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V_{SD}	-	0.67	-	V	V_{GS}=0V, I_F=1A, T_j=25°C
Reverse recovery time	t_{rr}	-	136.7	-	ns	V_R=400V, I_F=17A, di_F/dt=100A/μs; see table 8
Reverse recovery charge	Q_{rr}	-	0.741	-	uC	V_R=400V, I_F=17A, di_F/dt=100A/μs; see table 8
Peak reverse recovery current	I_{rrm}	-	10.28	-	A	V_R=400V, I_F=17A, di_F/dt=100A/μs; see table 8

4   Electrical characteristics diagram

Diagram 1: Typ. output characteristics	Diagram 2: Typ. Coss stored energy

$I_D=f(V_{DS}); T_j=25\ °C$; parameter: V_{GS}

$Eoss=f(VDS)$

Diagram 3: Typ. transfer characteristics	Diagram 4: Typ. gate charge

$I_D=f(V_{GS})$; parameter: T_j

$V_{GS}=f(Q_{gate}); I_D=19A$ pulsed; parameter: V_{DD}

Diagram 5: Drain-source breakdown voltage	Diagram 6: Typ. capacitances

$V_{BR(DSS)}$=f(T_j);I_D=1mA

C=f(V_{DS});V_{GS}=0V; f=1MHz

Diagram7:Typ. On-Resistance vs. Junction Temperature	Diagram 8: Safe operating area T_C=25 °C,
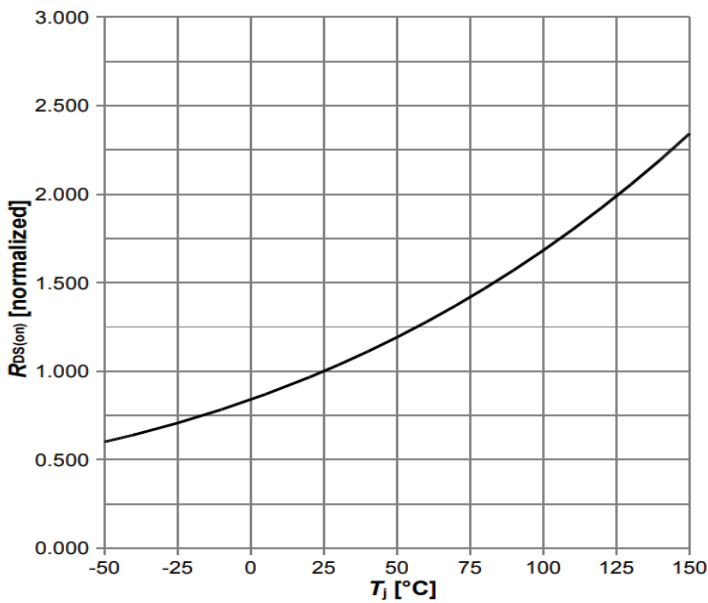
$R_{ds(on)}$=f(T_j);Vgs=10V/I_D=14A
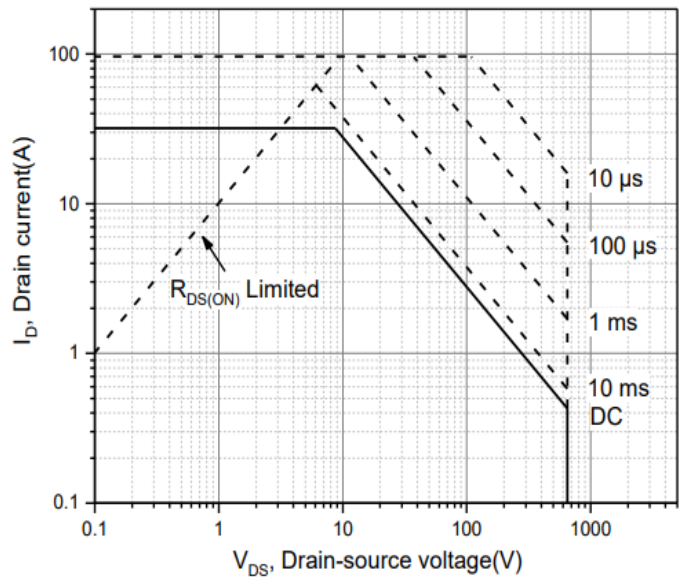
I_D=f(V_{DS}); T_C=25 °C; V_{GS}> 7V; D=0; parameter tp

Diagram 9: Typ. Power Dissipation	Diagram 10: Max. transient thermal impedance
P_{tot}=f(T_C)	Z_{thJC}=f(t_P); parameter: D=t_P/T
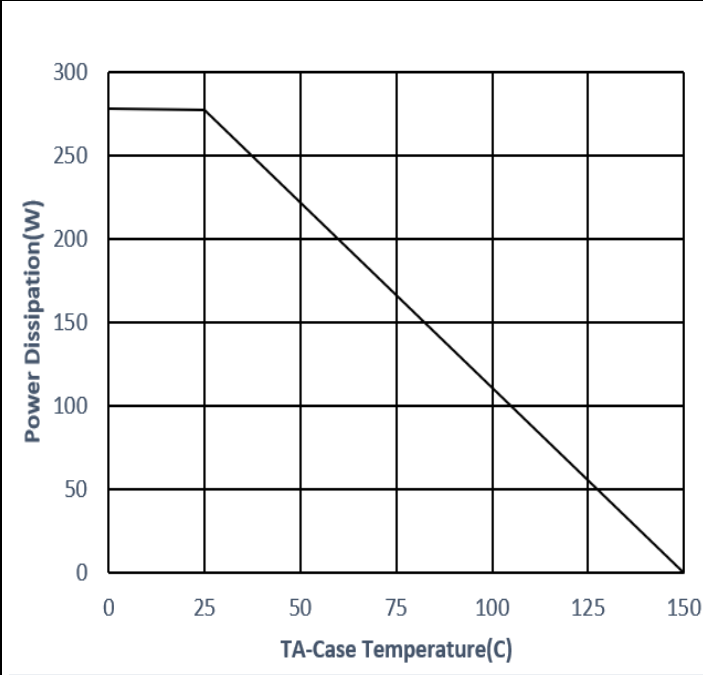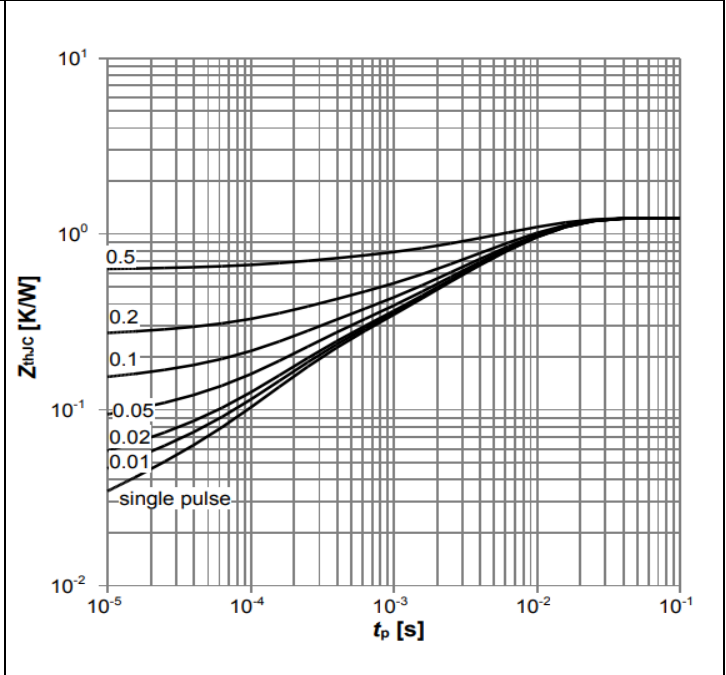
Diagram 11: Forward characteristics of reverse diode	Diagram 12: Typ. Drain-source on-state resistance
I_F=f(V_{DS});parameter: T_j	$R_{ds(on)}$=f(T_j);Tj=25C, Parameter :Vgs
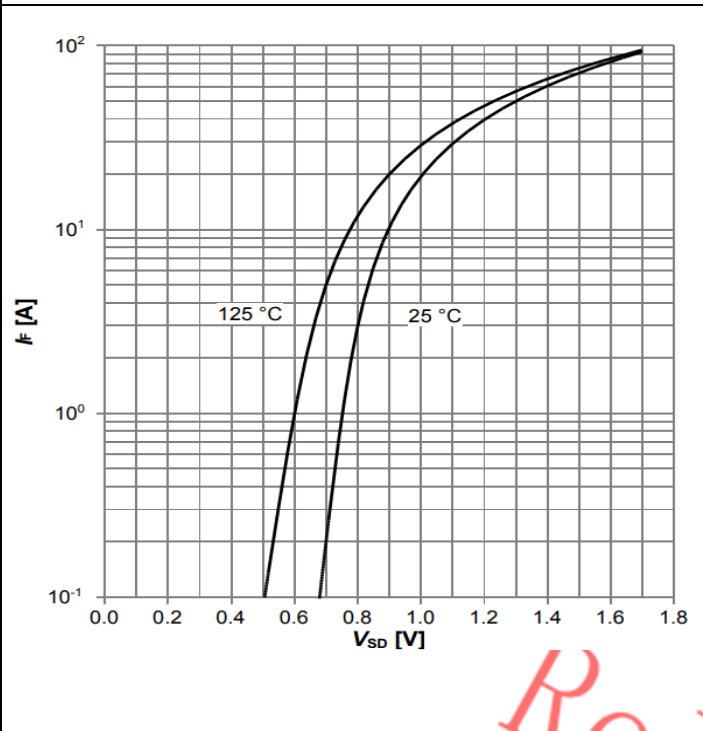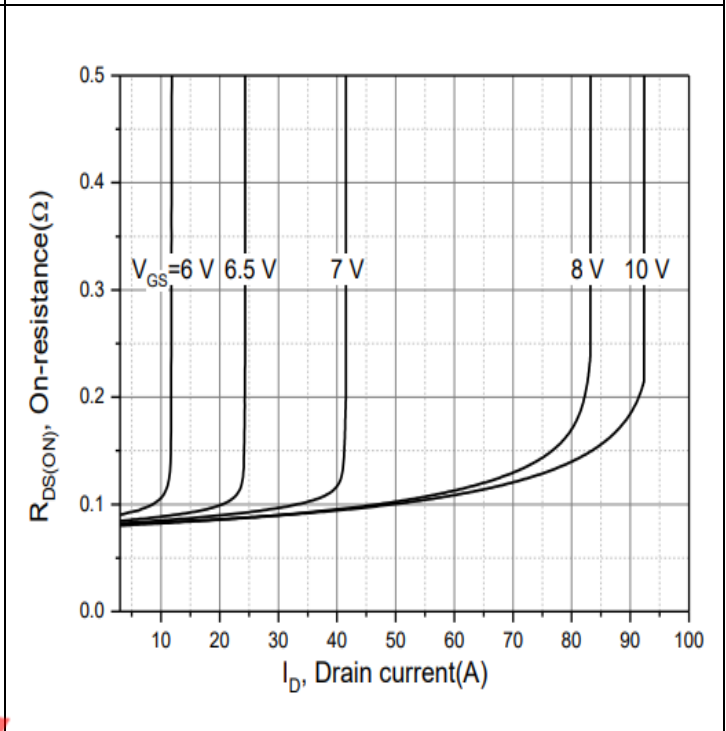
5 Test Circuits

Table 8 Diode characteristics

Test circuit for diode characteristics	Diode recovery waveform

Table 9 Switching times

Switching times test circuit for inductive load	Switching times waveform
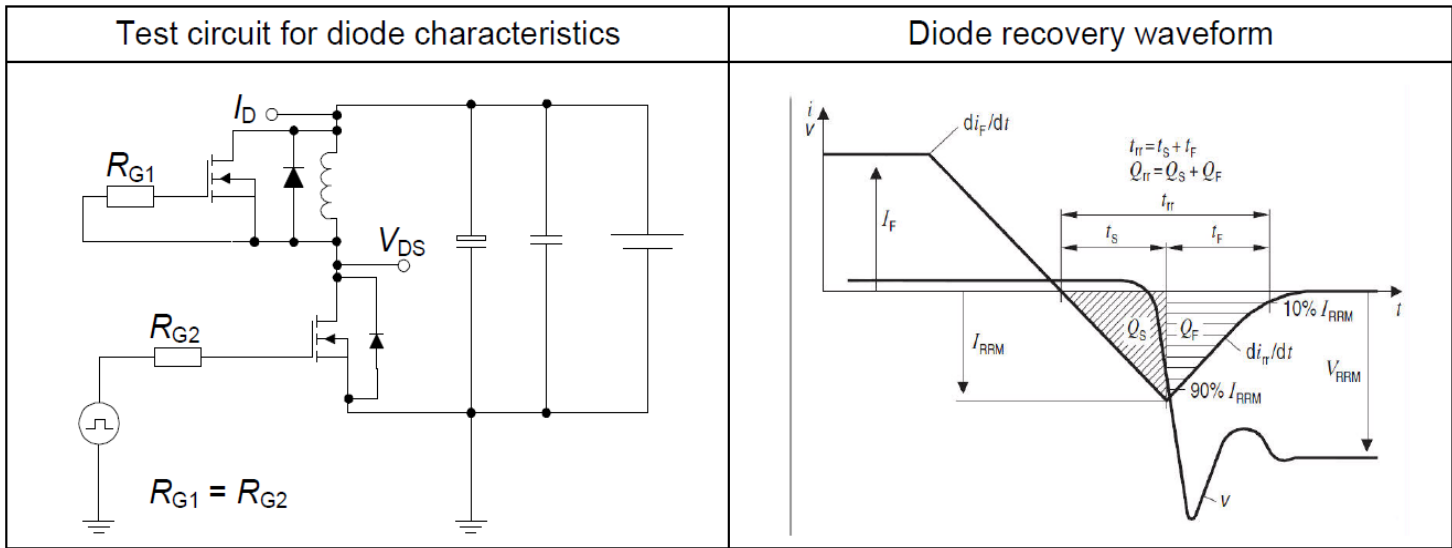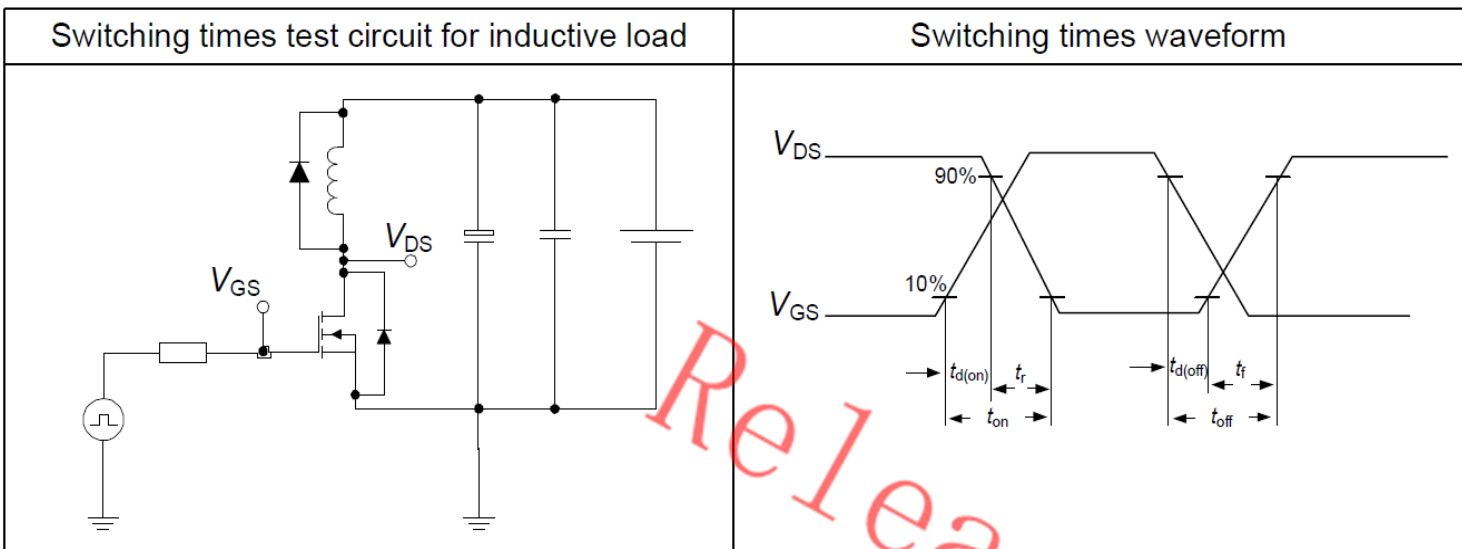
Table 10 Unclamped inductive load
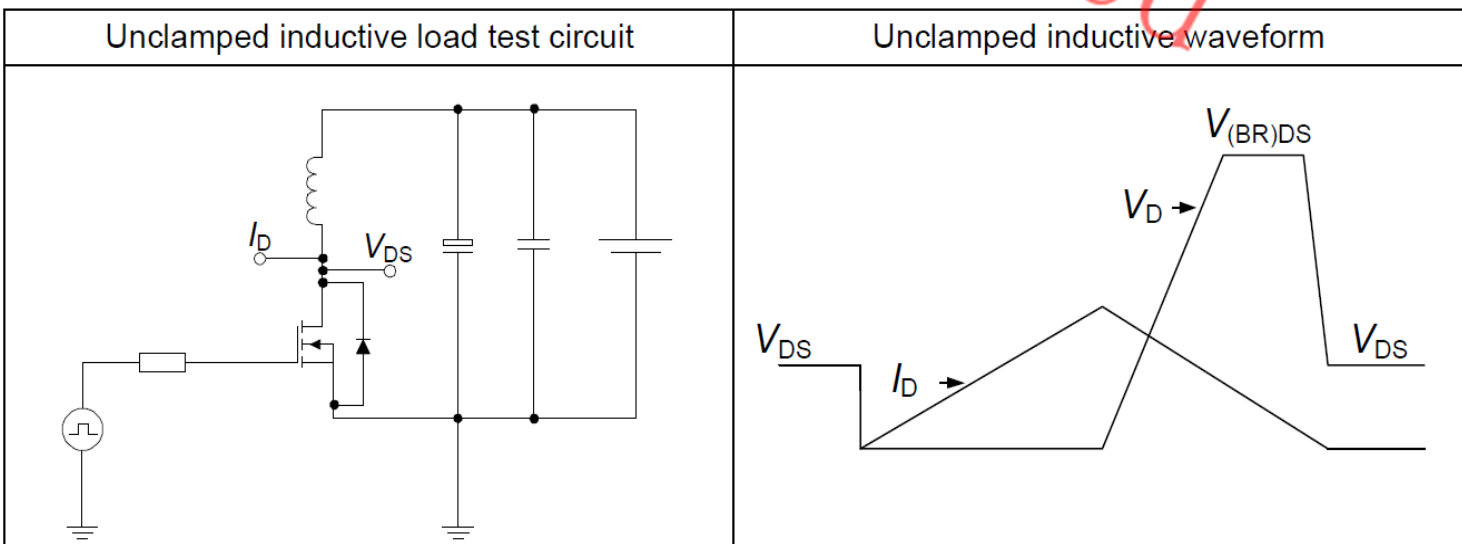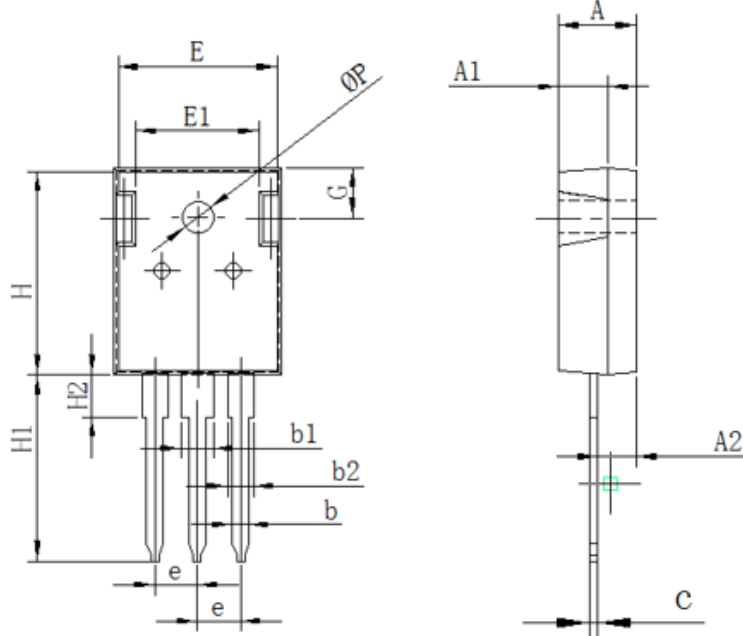
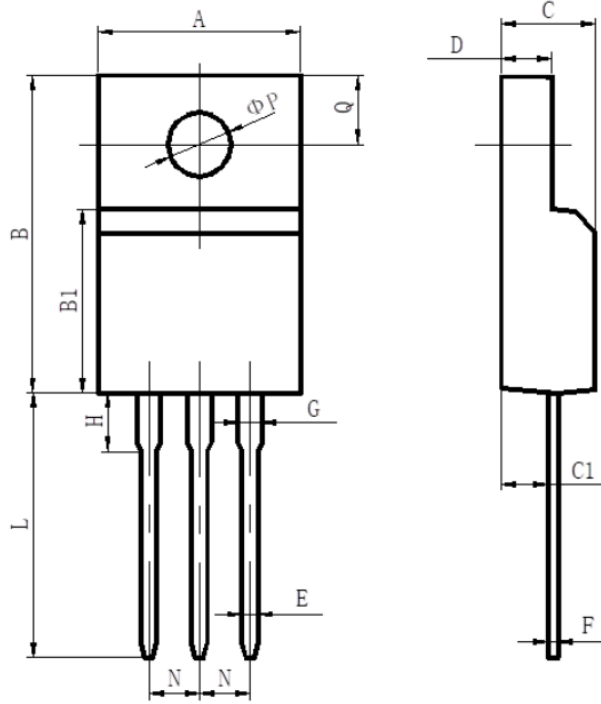| Unclamped inductive load test circuit	Unclamped inductive waveform

6 Package Outlines

| Symbol	单位　mm		
	Min	Nom	Max
A	4.8	5.00	5.20
A1	3.3	3.5	3.7
A2	2.20	2.40	2.60
b	1.00	1.2	1.40
b1	2.90	3.10	3.30
b2	1.90	2.10	2.30
c	0.50	0.60	0.70
e	5.25	5.45	5.65
E	15.2	15.7	16.2
E1	10.2	10.7	11.2
H	20.8	21	21.2
H1	19.5	20.0	20.5
H2	4.00	4.20	4.40
G	5.60	5.80	600
ΦP	3.50	3.70	3.90

Figure1：Outline PG-TO247(CD&HT)

项目	规范(mm)	
	MIN	MAX
A	9.70	10.30
B	15.50	16.10
B1	8.99	9.39
C	4.40	4.80
C1	2.15	2.55
D	2.50	2.90
E	0.70	0.90
F	0.40	0.60
G	1.12	1.42
H	3.40	3.80
L	12.6	13.6
N	2.34	2.74
Q	3.15	3.55
φP	3.00	3.30

Figure2：Outline PG-TO220F(HT)
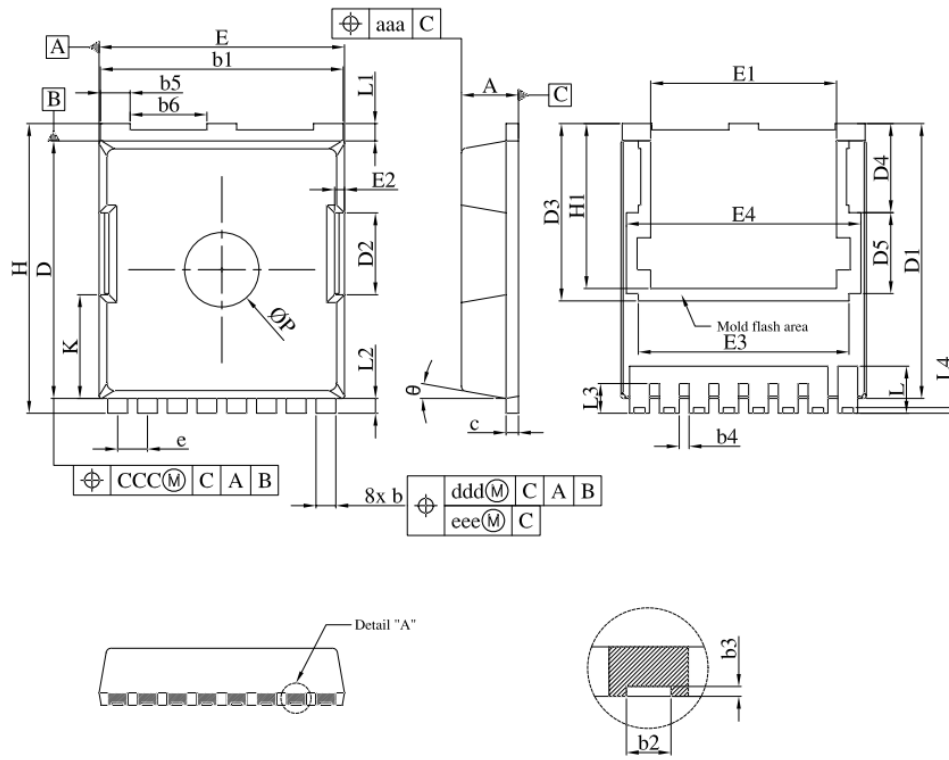
SYMBOL	COMMON MILLIMETER		
	MIN.	NOMINAL	MAX.
A	2.20	2.30	2.40
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b2	0.36	0.45	0.55
b3	0.05	0.100	/
b4	0.30	0.40	0.50
b5	1.10	1.20	1.30
b6	3.00	3.10	3.20
c	0.40	0.50	0.60
D	10.28	10.38	10.55
D1	10.98	11.08	11.18
D2	3.20	3.30	3.40
D3		7.15	
D4		3.59	
D5		3.26	
e	1.10	1.20	1.30
E	9.80	9.90	10.00
E1	7.40	7.50	7.60
E2	0.30	0.40	0.50
E3		8.50	
E4		9.46	
H	11.50	11.68	11.85
H1	6.55	6.65	6.75
K	4.08	4.18	4.28
L	1.60	1.90	2.10
L1	0.50	0.70	0.90
L2	0.50	0.60	0.70
L3	1.00	1.20	1.30
L4	0.13	0.23	0.33
P	2.85	3.00	3.15
θ		10° REF	
aaa		0.20	
ccc		0.20	
ddd		0.25	
eee		0.20	

Figure3：Outline PG-TOLL(JQ)

Revision History

Revision	Date	Subjects (major changes since last revision)
1.0	2020-09-15	Release version
1.1	2022-06-18	Updated TO247 POD to CD
1.2	2022-12-23	Updated Ciss/Coss/Crss&Trr/Qrr/Irrm, and added electrical characteristics diagram
1.3	2023-04-26	Added TO220F package
1.4	2023-08-22	Added TOLL-8L package